CLAIMS

What is claimed is:

1. A duplexer comprising:

a package substrate having layers stacked;

a transmission filter and a reception filter that are provided on an upper surface of a first layer that is one of the layers of the package substrate, the transmission and reception filters being acoustic wave filters;

a metal pattern provided on the upper surface of the first layer and formed to surround the transmission and reception filters;

a transmission line provided on an upper surface of a second layer that is one of the layers of the package substrate and is positionally lower than the first layer, the transmission line electrically connecting the transmission filter and a transmission terminal together; and

a reception line that is provided on the upper surface of the second layer and electrically connects the reception filter and a reception terminal,

wherein the thickness of the first layer is greater than that of the second layer.

2. The duplexer according to claim 1, where the transmission and reception lines are provided in an area other than an area defined by projecting the metal pattern onto the upper surface of the second layer.

3. The duplexer according to claim 1, further comprising: